

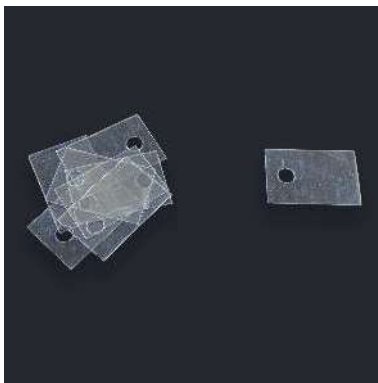


Mica panels are used in conjunction with insulating bushings for insulated assembly of semiconductors, e.g. on heat sinks.

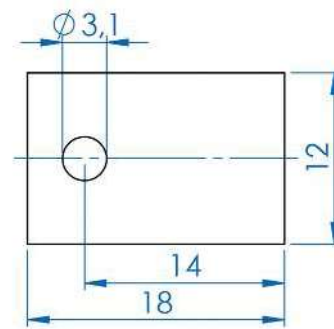
To avoid poorly conducting air bubbles, it is recommended to use heat-conducting paste or heat-conducting foils.

General technical values: Colour: colourless, transparent
 Thickness: 0.05 mm
 Thickness tolerance: + 0.01 / - 0.02 mm
 Resistance to heat: + 550°C
 Dielectric strength: approx. 2.5 KV

GL 530



For Casing: **TO 220**

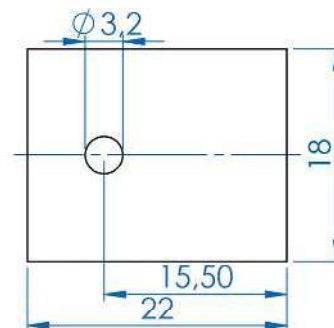


Rth: [K/W]: **1.25**

GL 535/N

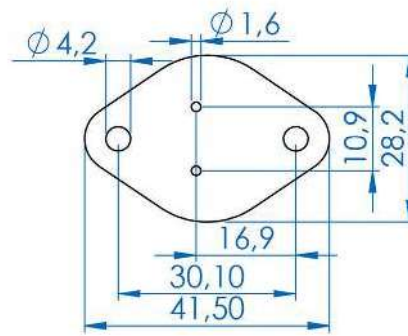


For Casing: **TOP 3 (TO218)**



Rth: [K/W]: **0.8**

GL 510



For Casing: **TO 3**

Rth: [K/W]: **0.3**

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